



Laird™ Tgon™ 820

Used where electrical isolation is not required, Tgon 800 is ideal for where electrical contact and thermal transfer are desired. Its unique grain-oriented, plate-like structure provides a high thermal conductivity of 240 W/mK in the XY plane and 5 W/mK through the z-axis. Tgon 800 can be supplied in 12" x 18" (305mm x 457mm) or 18" x 24" (457mm x 610mm) sheets, rolls or die-cut to specific configurations. It is also available with proprietary pressure sensitive adhesive on one side. This adhesive coating is the thinnest available, minimizing any impact on thermal performance.

TECHNICAL DATA SHEET | (EFFECTIVE 24FEB25)

Laird™ Tgon™ 820

PHYSICAL PROPERTY	TEST METHOD	UNIT	VALUE
Construction		-	Flexible Graphite
Color		-	Pewter
Thickness		in mm	0.02 0.51
Thickness Tolerance		in mm	0.002 0.05
Density	Helium Pycnometer	g/cc	2.2
Hardness	ASTM D2240	Shore A	85
Tensile Strength	ASTM D412	psi	650
Outgassing TML	ASTM E595	%	0.15
Outgassing CVCM	ASTM E595	%	0.09
UL Flammability Rating	UL 94	-	V-0
Temperature Range		°C	-240 to 300
Thermal Conductivity (Z Axis)	ASTM D5470 (modified)	w/mk	5
Thermal Conductivity (XY Axis)	ASTM D5470 (modified)	w/mk	240
Thermal Resistance @ 100 psi	ASTM D5470 (modified)	°C-in ² /w	0.17
Thermal Resistance @ 681 psi	ASTM D5470 (modified)	°C-in ² /w	1.07
Volume Resistivity (In-Plane)	ASTM D257	ohm-cm	11 × 10 ⁻⁵